

W-laminates for structural divertor applications: W-Ti laminates

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Content

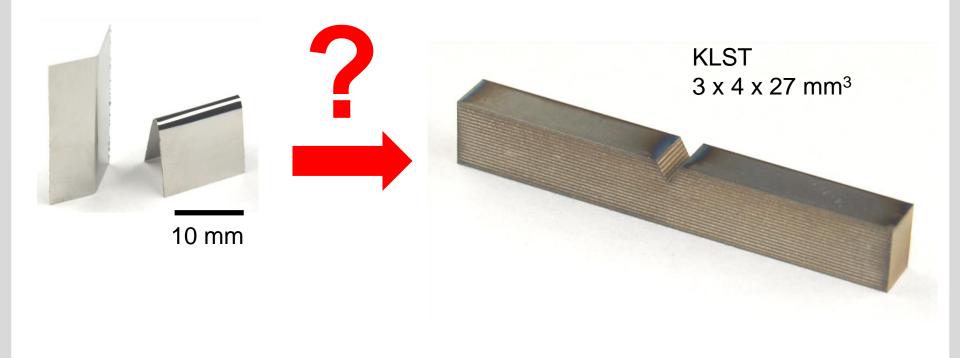


- W-Ti laminates
 - Charpy
 - SEM
 - Auger
 - Outlook: 1000 h / 1000°C

Main question



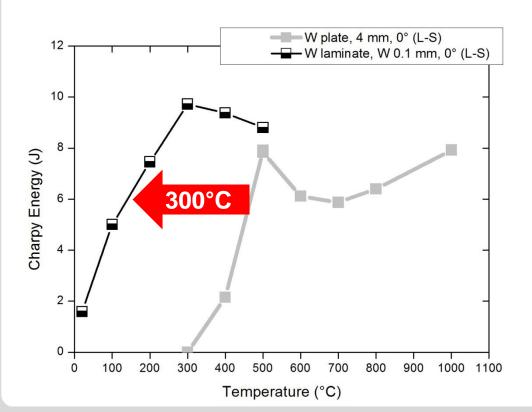
Is it possible to expand the ductile properties of a W-foil to the bulk?



W-laminates: Charpy impact tests



- Can the ductile properties of a W-foil be transferred to the bulk?
 - As-received: improvement of 300°C

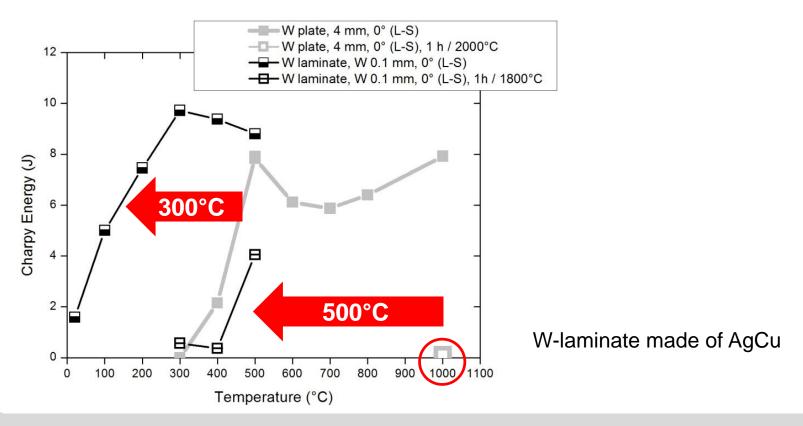


W-laminate made of AgCu

W-laminates: Charpy impact tests



- Can the ductile properties of a W-foil be transferred to the bulk?
 - As-received: improvement of 300°C
 - Recrystallized: improvement of 500°C



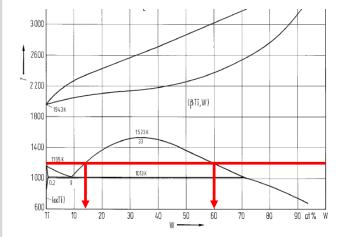
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W-laminates: diffusion bonding with Ti

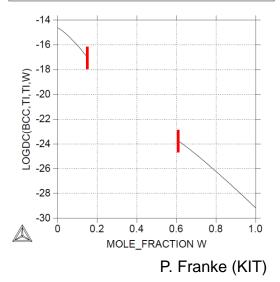


W-Ti diffusion bonding at 900°C

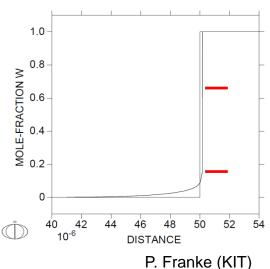
W-Ti phase diagram



(inter-) diffusion coefficients at 900°C



Interface, 900°C: 0 s, 1 h

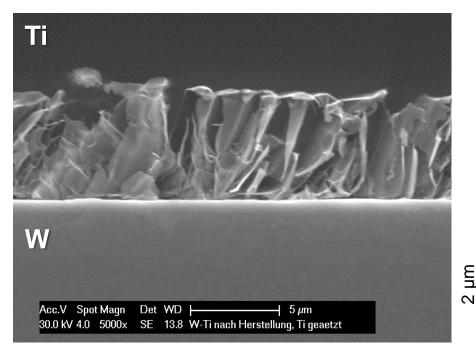


- 2 solid solutions after cooling down
- Diffusion: W in Ti > Ti in W
- Phase boundaries
- Miscibility gap

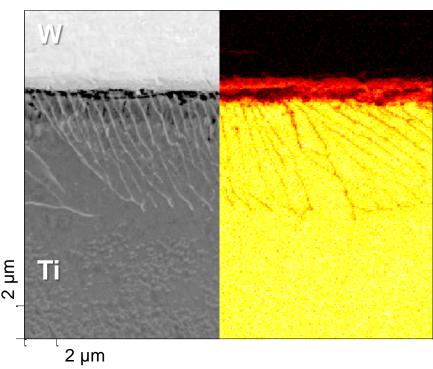
W-laminates: diffusion bonding with Ti



W-Ti diffusion bonding at 900°C → cooling down at RT



- **Eutectoid transformation**
- WIDMANSTÄTTEN-kind structure
- W needles in α -Ti matrix



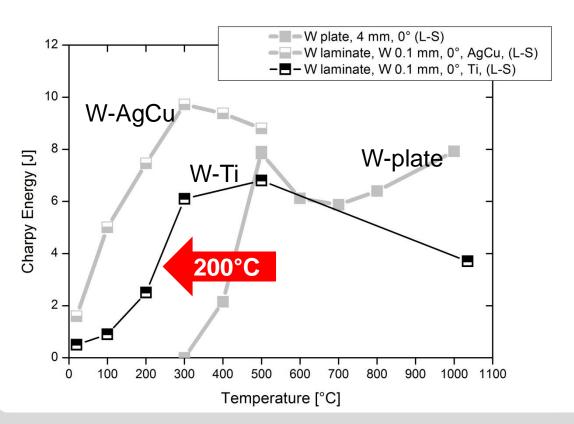
Quantitative scale of Ti: yellow = max., black = min.

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W-laminates: diffusion bonding with Ti



- Charpy impact properties
 - Improvement of 200°C compared to W-plate material









Thank you for your attention

The authors are grateful to







